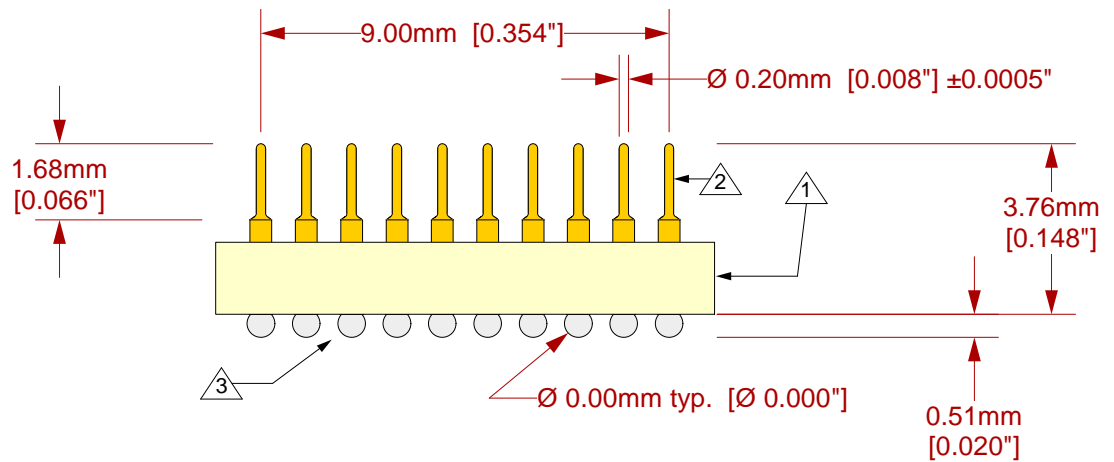


Top View




Side View

Description: Giga-snaP BGA SMT Foot
 100 position male terminal pins to solder balls
 (1.0mm [0.039\"] centers, 10x10 array)

Tolerances: diameters $\pm 0.03\text{mm}$ [± 0.001 \"], PCB perimeters $\pm 0.13\text{mm}$ [± 0.005 \"], PCB thicknesses $\pm 0.18\text{mm}$ [± 0.007 \"], pitches (from true position) $\pm 0.08\text{mm}$ [± 0.003 \"], all other tolerances $\pm 0.13\text{mm}$ [± 0.005 \"] unless stated otherwise. Materials and specifications are subject to change without notice.

- ① Substrate: $1.59\text{mm} \pm 0.18\text{mm}$ [0.0625 \" ± 0.007 \"]
FR4/G10 or equivalent high temp material.
- ② Pins: material- Brass Alloy 360 1/2 hard; finish-
 $0.25\mu\text{m}$ [10μ \" Au over $1.27\mu\text{m}$ [50μ \" Ni (min.).
- ③ Balls: Eutectic 63/37 SnPb.

	SF-BGA100B-B-41 Drawing	Status: Released	Scale: 6:1	Rev: C
	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen	Date: 7/26/04	
		File: SF-BGA100B-B-41 Dwg	Modified: 3/30/05	